

MECHANICAL DESCRIPTION

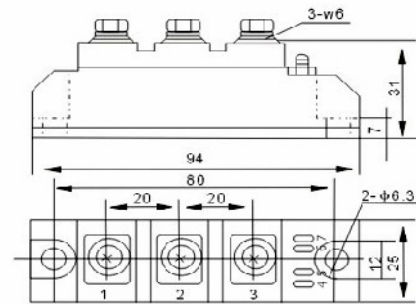
The MTC, MFC module, combines the excellent thermal performances obtained by the usage of exposed direct bonded copper substrate, with advanced compact simple package solution and simplified internal structure with minimized number of interfaces.

FEATURES

- High voltage
- Industrial standard package
- Low thermal resistance
- Designed and qualified for industrial level
- Excellent thermal performances obtained by the usage of exposed direct bonded copper substrate
- High surge capability
- Easy mounting on heatsink

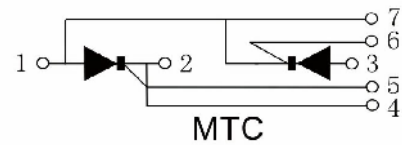


M01

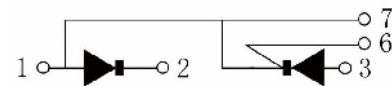


APPLICATIONS

These modules are intended for general purpose high voltage applications such as high voltage regulated power supplies, lighting circuits, temperature and motor speed control circuits, UPS and battery charger.



MTC



MFC

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	90A	110A	UNITS
$I_{T(AV)}$ or $I_{F(AV)}$	$T_c=85^\circ\text{C}$	90	110	A
I_{TSM} I_{FSM}	50 Hz $T_{Jm}=125^\circ\text{C}$	2,000	2,400	
	60 Hz $T_{Jm}=125^\circ\text{C}$	2,132	2,558	
I^2t	50 Hz $T_{Jm}=125^\circ\text{C}$	20.40	29.30	kA ² s
	60 Hz $T_{Jm}=125^\circ\text{C}$	19.24	27.63	
V_{RRM}	Range	600 to 2000	600 to 2000	V
T_{Stg}		-40 to 125	-40 to 125	°C
T_J				

ON-STATE CONDUCTION						
PARAMETER	SYMBOL	TEST CONDITIONS		90A	110A	UNITS
Maximum average on-state current (thyristors)	$I_{T(AV)}$	180° conduction, half sine wave, $T_c = 85^\circ\text{C}$		90	110	A
Maximum average forward current (diodes)	$I_{F(AV)}$					
Maximum peak, one-cycle non-repetitive on-state or forward current	I_{TSM} or I_{FSM}	$t = 10\text{ ms}$	80 % V_{RRM}	Sinusoidal half wave, initial $T_J = T_J$ maximum	2,000	2,400
		$t = 8.3\text{ ms}$	reapplied		2,132	2,558
Maximum I^2t for fusing	I^2t	$t = 10\text{ ms}$	No voltage reapplied	Initial $T_J = T_J$ maximum	20.40	29.30
		$t = 8.3\text{ ms}$			19.24	27.63
Maximum value or threshold voltage	$V_{T(TO)}$	$T_J = T_J$ maximum		0.97		V
Maximum value of on-state slope resistance	r_t	$T_J = T_J$ maximum		1.26	1.18	m
Maximum peak on-state or forward voltage	V_{TM}	$I_{TM} = \quad \times I_{T(AV)}$	$T_J = 25^\circ\text{C}$	1.30	1.40	V
	V_{FM}	$I_{FM} = \quad \times I_{F(AV)}$				
Maximum non-repetitive rate of rise of turned on current	di/dt	$T_J = 25^\circ\text{C}$, from 0.67 V_{DRM} , $I_{TM} = \quad \times I_{T(AV)}$, $I_g = 500\text{ mA}$, $t_r < 0.5\ \mu\text{s}$, $t_f > 6\ \mu\text{s}$		100		A/ μs
Maximum holding current	I_H	$T_J = 25^\circ\text{C}$, anode supply = 6 V, resistive load, gate open circuit		250		mA
Maximum latching current	I_L	$T_J = 25^\circ\text{C}$, anode supply = 6 V, resistive load		600		

Notes:

$$\text{Average power} = V_{T(TO)} \times I_{T(AV)} + 2.56 r_t \times (I_{T(AV)})^2$$

TRIGGERING						
PARAMETER	SYMBOL	TEST CONDITIONS		90A	110A	UNITS
Maximum peak gate power	P_{GM}	$T_J = 25^\circ\text{C}$, 50Hz, 3s		8	10	W
Maximum average gate power	$P_{G(AV)}$	$T_J = 25^\circ\text{C}$, 50Hz, 3s		2	3	
Maximum peak gate current	I_{GM}			2	3	A
Maximum peak negative gate voltage	- V_{GM}			10		V
Maximum gate voltage required to trigger	V_{GT}	$T_J = 25^\circ\text{C}$	Anode supply = 6 V resistive load	3	3.5	
Maximum gate current required to trigger	I_{GT}	$T_J = 25^\circ\text{C}$	Anode supply = 6 V resistive load	100		mA
Maximum gate voltage that will not trigger	V_{GD}	$T_J = 125^\circ\text{C}$, rated V_{DRM} applied		0.20		V
Maximum gate current that will not trigger	I_{GD}	$T_J = 125^\circ\text{C}$, rated V_{DRM} applied		6		mA

BLOCKING

PARAMETER	SYMBOL	TEST CONDITIONS	90A	110A	UNITS
Maximum peak reverse and off-state leakage current at V_{RRM} , V_{DRM}	I_{RRM} , I_{DRM}	$T_J = 125\text{ }^\circ\text{C}$, gate open circuit	10	12	mA
Maximum RMS insulation voltage	V_{ISO}	50 Hz	2500 (1 min)		V
Maximum critical rate of rise of off-state voltage	dV/dt	$T_J = 125\text{ }^\circ\text{C}$, linear to $0.67 V_{DRM}$	500		V/ μs

THERMAL AND MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	90A	110A	UNITS
Junction operating and storage temperature range	T_J , T_{Stg}		- 40 to 125		$^\circ\text{C}$
Maximum internal thermal resistance, junction to case per leg	R_{thJC}	DC operation	0.28	0.25	$^\circ\text{C/W}$
Typical thermal resistance, case to heatsink per module	R_{thCS}	Mounting surface flat, smooth and greased	0.1		
Mounting torque ?10 %	to heatsink	A mounting compound is recommended and the torque should be rechecked after a period of 3 h to allow for the spread of the compound.	3		Nm
	busbar		2		
Approximate weight			150		g
Case style			M01		